

QL4090 QuickRAM Data Sheet



- • • • • **90,000 Usable PLD Gate QuickRAM ESP Combining Performance, Density and Embedded RAM**

Device Highlights

High Performance & High Density

- 90,000 Usable PLD Gates with 316 I/Os
- 300 MHz 16-bit Counters, 400 MHz Datapaths, 160+ MHz FIFOs
- 0.35µm four-layer metal non-volatile CMOS process for smallest die sizes

High Speed Embedded SRAM

- 22 dual-port RAM modules, organized in user-configurable 1,152 bit blocks
- 5 ns access times, each port independently accessible
- Fast and efficient for FIFO, RAM, and ROM functions

Easy to Use / Fast Development Cycles

- 100% routable with 100% utilization and complete pin-out stability
- Variable-grain logic cells provide high performance and 100% utilization
- Comprehensive design tools include high quality Verilog/VHDL synthesis

Advanced I/O Capabilities

- Interfaces with both 3.3 V and 5.0 V devices
- PCI compliant with 3.3 V and 5.0 V busses for -1/-2/-3/-4 speed grades
- Full JTAG boundary scan
- I/O Cells with individually controlled Registered Input Path and Output Enables

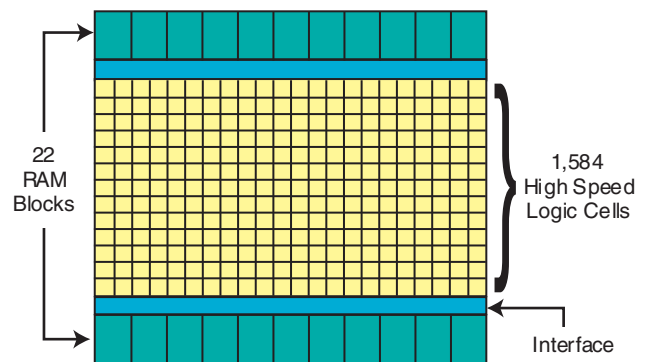


Figure 1: QuickRAM Block Diagram

Architecture Overview

The QuickRAM™ family of ESPs (Embedded Standard Products) offers FPGA logic in combination with Dual-Port SRAM modules. The QL4090 is a 90,000 usable PLD gate member of the QuickRAM family of ESPs. QuickRAM ESPs are fabricated on a 0.35 μm four-layer metal process using QuickLogic's patented ViaLink™ technology to provide a unique combination of high performance, high density, low cost, and extreme ease-of-use.

The QL4090 contains 1,584 logic cells and 22 Dual Port RAM modules (see [Figure 1](#)). Each RAM module has 1,152 RAM bits, for a total of 25,344 bits. RAM Modules are Dual Port (one read port, one write port) and can be configured into one of four modes: 64 (deep) x18 (wide), 128x9, 256x4, or 512x2 (see [Figure 4](#)). With a maximum of 82 I/Os, the QL4090 is available in 208-pin PQFP, 208-pin CQFP 240-pin PQFP and 456-pin PBGA packages.

Designers can cascade multiple RAM modules to increase the depth or width allowed in single modules by connecting corresponding address lines together and dividing the words between modules (see [Figure 2](#)). This approach allows up to 512-deep configurations as large as 16 bits wide in the smallest QuickRAM device and 44 bits wide in the largest device.

Software support for the complete QuickRAM family, including the QL4090, is available through two basic packages. The turnkey QuickWorks™ package provides the most complete ESP software solution from design entry to logic synthesis, to place and route, to simulation. The QuickTools™ packages provides a solution for designers who use Cadence, Exemplar, Mentor, Synopsys, Synplicity, Viewlogic, Aldec, or other third-party tools for design entry, synthesis, or simulation.

The QuickLogic variable grain logic cell features up to 16 simultaneous inputs and 5 outputs within a cell that can be fragmented into 5 independent cells. Each cell has a fan-in of 29 including register and control lines (see [Figure 3](#)).

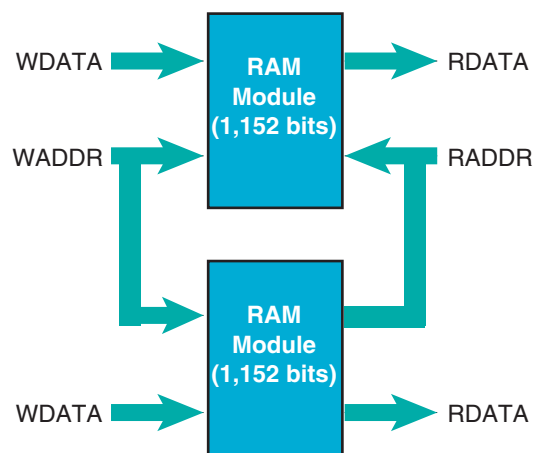


Figure 2: QuickRAM Module Bits

Product Summary

Total of 316 I/O Pins

- 308 bi-directional input/output pins, PCI-compliant for 5.0 V and 3.3 V buses for -1/-2/-3/-4 speed grades
- 8 high-drive input/distributed network pins

Eight Low-Skew Distributed Networks

- Two array clock/control networks available to the logic cell flip-flop clock, set and reset inputs—each driven by an input-only pin
- Six global clock/control networks available to the logic cell F1, clock, set and reset inputs and the input and I/O register clock, reset and enable inputs as well as the output enable control—each driven by an input-only or I/O pin, or any logic cell output or I/O cell feedback

High Performance Silicon

- Input + logic cell + output total delays under 6 ns
- Data path speeds over 400 MHz
- Counter speeds over 300 MHz
- FIFO speeds over 160+ MHz

AC Characteristics at $V_{CC} = 3.3\text{ V}$, $T_A = 25^\circ\text{ C}$ ($K = 1.00$)

To calculate delays, multiply the appropriate K factor from **Table 10: Operating Range** by the following numbers in the tables provided.

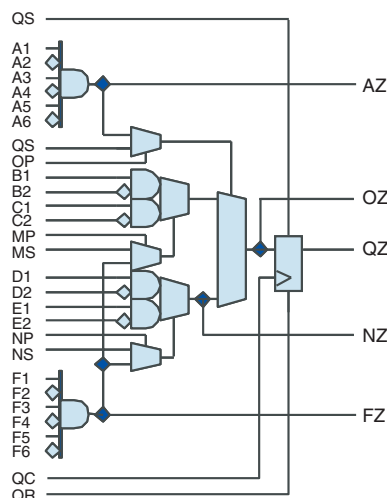


Figure 3: QuickRAM Logic Cell

Table 1: Logic Cell

Symbol	Parameter	Propagation Delays (ns) Fanout (5)				
		1	2	3	4	5
t_{PD}	Combinatorial Delay ^a	1.4	1.7	1.9	2.2	3.2
t_{SU}	Setup Time ^a	1.7	1.7	1.7	1.7	1.7
t_H	Hold Time	0.0	0.0	0.0	0.0	0.0
t_{CLK}	Clock to Q Delay	0.7	1.0	1.2	1.5	2.5
t_{CWHI}	Clock High Time	1.2	1.2	1.2	1.2	1.2
t_{CWLO}	Clock Low Time	1.2	1.2	1.2	1.2	1.2
t_{SET}	Set Delay	1.0	1.3	1.5	1.8	2.8
t_{RESET}	Reset Delay	0.8	1.1	1.3	1.6	2.6
t_{SW}	Set Width	1.9	1.9	1.9	1.9	1.9
t_{RW}	Reset Width	1.8	1.8	1.8	1.8	1.8

a. These limits are derived from a representative selection of the slowest paths through the QuickRAM logic cell including typical net delays. Worst case delay values for specific paths should be determined from timing analysis of your particular design.

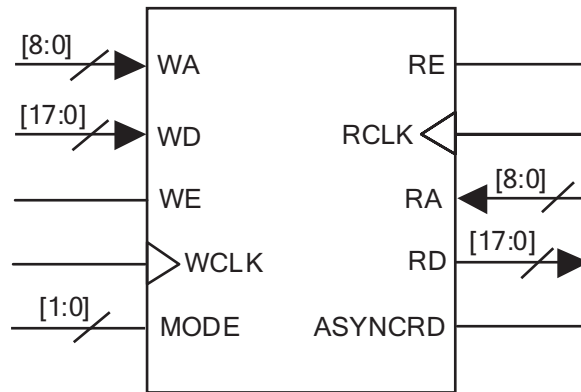


Figure 4: QuickRAM Module

Table 2: RAM Cell Synchronous Write Timing

Symbol	Parameter	Propagation Delays (ns) Fanout				
		1	2	3	4	5
t_{SWA}	WA Setup Time to WCLK	1.0	1.0	1.0	1.0	1.0
t_{HWA}	WA Hold Time to WCLK	0.0	0.0	0.0	0.0	0.0
t_{SWD}	WD Setup Time to WCLK	1.0	1.0	1.0	1.0	1.0
t_{HWD}	WD Hold Time to WCLK	0.0	0.0	0.0	0.0	0.0
t_{SWE}	WE Setup Time to WCLK	1.0	1.0	1.0	1.0	1.0
t_{HWE}	WE Hold Time to WCLK	0.0	0.0	0.0	0.0	0.0
t_{WCRD}	WCLK to RD (WA=RA) ^a	5.0	5.3	5.6	5.9	7.1

a. Stated timing for worst case Propagation Delay over process variation at $V_{CC} = 3.3$ V and $T_A = 25^\circ$ C. Multiply by the appropriate Delay Factor, K, for speed grade, voltage and temperature settings as specified in the Operating Range.

Table 3: RAM Cell Synchronous Read Timing

Symbol	Parameter	Propagation Delays (ns) Fanout				
		1	2	3	4	5
Logic Cells						
t_{SRA}	RA Setup Time to RCLK	1.0	1.0	1.0	1.0	1.0
t_{HRA}	RA Hold Time to RCLK	0.0	0.0	0.0	0.0	0.0
t_{SRE}	RE Setup Time to RCLK	1.0	1.0	1.0	1.0	1.0
t_{HRE}	RE Hold Time to RCLK	0.0	0.0	0.0	0.0	0.0
t_{RCD}	RCLK to RD ^a	4.0	4.3	4.6	4.9	6.1

a. Stated timing for worst case Propagation Delay over process variation at $V_{CC} = 3.3$ V and $T_A = 25^\circ$ C. Multiply by the appropriate Delay Factor, K, for speed grade, voltage and temperature settings as specified in the Operating Range.

Table 4: RAM Cell Asynchronous Read Timing

Symbol	Parameter	Propagation Delays (ns) Fanout				
		1	2	3	4	5
RPDRD	RA to RD ^a	3.0	3.3	3.6	3.9	5.1

a. Stated timing for worst case Propagation Delay over process variation at $V_{CC} = 3.3$ V and $T_A = 25^\circ$ C. Multiply by the appropriate Delay Factor, K, for speed grade, voltage and temperature settings as specified in the Operating Range.

Table 5: Input-Only / Clock Cells

Symbol	Parameter	Propagation Delays (ns) Fanout						
		1	2	3	4	8	12	24
t_{IN}	High Drive Input Delay	1.5	1.6	1.8	1.9	2.4	2.9	4.4
t_{INI}	High Drive Input, Inverting Delay	1.6	1.7	1.9	2.0	2.5	3.0	4.5
t_{ISU}	Input Register Set-Up Time	3.1	3.1	3.1	3.1	3.1	3.1	3.1
t_{IH}	Input Register Hold Time	0.0	0.0	0.0	0.0	0.0	0.0	0.0
t_{CLK}	Input Register Clock To Q	0.7	0.8	1.0	1.1	1.6	2.1	3.6
t_{IRST}	Input Register Reset Delay	0.6	0.7	0.9	1.0	1.5	2.0	3.5
t_{IESU}	Input Register Clock Enable Setup Time	2.3	2.3	2.3	2.3	2.3	2.3	2.3
t_{IEH}	Input Register Clock Enable Hold Time	0.0	0.0	0.0	0.0	0.0	0.0	0.0

Table 6: Clock Cells

Symbol	Parameter	Propagation Delays (ns) Fanout ^a						
		1	2	3	4	8	10	11
t_{ACK}	Array Clock Delay	1.2	1.2	1.3	1.3	1.5	1.6	1.7
t_{GCKP}	Global Clock Pin Delay	0.7	0.7	0.7	0.7	0.7	0.7	0.7
t_{GCKB}	Global Clock Buffer Delay	0.8	0.8	0.9	0.9	1.1	1.2	1.3

a. The array distributed networks consist of 40 half columns and the global distributed networks consist of 44 half columns, each driven by an independent buffer. The number of half columns used does not affect clock buffer delay. The array clock has up to 8 loads per half column. The global clock has up to 11 loads per half column.

Table 7: I/O Cell Input Delays

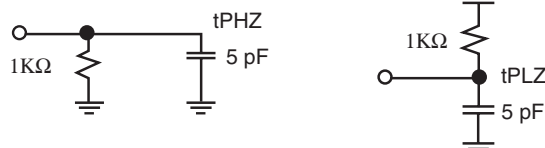
Symbol	Parameter	Propagation Delays (ns) Fanout ^a					
		1	2	3	4	8	10
$t_{I/O}$	Input Delay (bidirectional pad)	1.3	1.6	1.8	2.1	3.1	3.6
t_{ISU}	Input Register Set-Up Time	3.1	3.1	3.1	3.1	3.1	3.1
t_{IH}	Input Register Hold Time	0.0	0.0	0.0	0.0	0.0	0.0
t_{IOCLK}	Input Register Clock to Q	0.7	1.0	1.2	1.5	2.5	3.0
t_{IORST}	Input Register Reset Delay	0.6	0.9	1.1	1.4	2.4	2.9
t_{IESU}	Input Register Clock Enable Set-Up Time	2.3	2.3	2.3	2.3	2.3	2.3
t_{IEH}	Input Register Clock Enable Hold Time	0.0	0.0	0.0	0.0	0.0	0.0

- a. Stated timing for worst case Propagation Delay over process variation at $V_{CC} = 3.3\text{ V}$ and $T_A = 25^\circ\text{ C}$. Multiply by the appropriate Delay Factor, K, for speed grade, voltage and temperature settings as specified in the Operating Range.

Table 8: I/O Cell Output Delays

Symbol	Parameter	Propagation Delays (ns) Output Load Capacitance (pF)				
		3	50	75	100	150
t_{OUTLH}	Output Delay Low to High	2.1	2.5	3.1	3.6	4.7
t_{OUTHl}	Output Delay High to Low	2.2	2.6	3.2	3.7	4.8
t_{PZH}	Output Delay Tri-state to High	1.2	1.7	2.2	2.8	3.9
t_{PZL}	Output Delay Tri-state to Low	1.6	2.0	2.6	3.1	4.2
t_{PHZ}	Output Delay High to Tri-state ^a	2.0	-	-	-	-
t_{PLZ}	Output Delay High to Tri-state ^a	1.2	-	-	-	-

- a. The following loads are used for t_{PHZ}



DC Characteristics

The DC specifications are provided in the tables below.

Table 9: Absolute Maximum Ratings

Parameter	Value	Parameter	Value
V _{CC} Voltage	-0.5 to 4.6 V	DC Input Current	±20 mA
V _{CCIO} Voltage	-0.5 to 7.0 V	ESD Pad Protection	±2000 V
Input Voltage	-0.5 V to V _{CCIO} +0.5 V	Storage Temperature	-65° C to +150° C
Latch-up Immunity	±200 mA	Lead Temperature	300° C

Table 10: Operating Range

Symbol	Parameter		Military		Industrial		Commercial		Unit
			Min	Max	Min	Max	Min	Max	
V _{CC}	Supply Voltage		3.0	3.6	3.0	3.6	3.0	3.6	V
V _{CCIO}	I/O Input Tolerance Voltage		3.0	5.5	3.0	5.5	3.0	5.25	V
T _A	Ambient Temperature		-55	-	-40	85	0	70	°C
T _C	Case Temperature		-	125	-	-	-	-	°C
K	Delay Factor	-0 Speed Grade	0.42	2.03	0.43	1.90	0.46	1.85	n/a
		-1 Speed Grade	0.42	1.64	0.43	1.54	0.46	1.50	n/a
		-2 Speed Grade	0.42	1.37	0.43	1.28	0.46	1.25	n/a
		-3 Speed Grade			0.43	0.90	0.46	0.88	n/a
		-4 Speed Grade			0.43	0.82	0.46	0.80	n/a

Table 11: DC Characteristics

Symbol	Parameter	Conditions	Min	Max	Units
V_{IH}	Input HIGH Voltage		$0.5 V_{CC}$	$V_{CCIO} + 0.5$	V
V_{IL}	Input LOW Voltage		-0.5	$0.3V_{CC}$	V
V_{OH}	Output HIGH Voltage	$I_{OH} = -12 \text{ mA}$	2.4		V
		$I_{OH} = -500 \mu\text{A}$	$0.9 V_{CC}$		V
V_{OL}	Output LOW Voltage	$I_{OL} = 16 \text{ mA}^a$		0.45	V
		$I_{OL} = 1.5 \text{ mA}$		$0.1 V_{CC}$	V
I_I	I or I/O Input Leakage Current	$V_I = V_{CCIO} \text{ or GND}$	-10	10	μA
I_{OZ}	3-State Output Leakage Current	$V_I = V_{CCIO} \text{ or GND}$	-10	10	μA
C_I	Input Capacitance ^b			10	pF
I_{OS}	Output Short Circuit Current ^c	$V_O = \text{GND}$	-15	-180	mA
		$V_O = V_{CC}$	40	210	mA
I_{CC}	D.C. Supply Current ^d	$V_I, V_{IO} = V_{CCIO} \text{ or GND}$	0.50 (typ)	2	mA
I_{CCIO}	D.C. Supply Current on V_{CCIO}		0	100	μA

a. Applies only to -1/-2/-3/-4 commercial grade devices. These speed grades are also PCI-compliant. All other devices have 8 mA IOL specifications.

b. Capacitance is sample tested only. Clock pins are 12 pF maximum.

c. Only one output at a time. Duration should not exceed 30 seconds.

d. For -1/-2/-3/-4 commercial grade devices only. Maximum I_{CC} is 3 mA for -0 commercial grade and all industrial grade devices. and 5 mA for all military grade devices. For AC conditions, contact QuickLogic customer applications group.

Kv and Kt Graphs

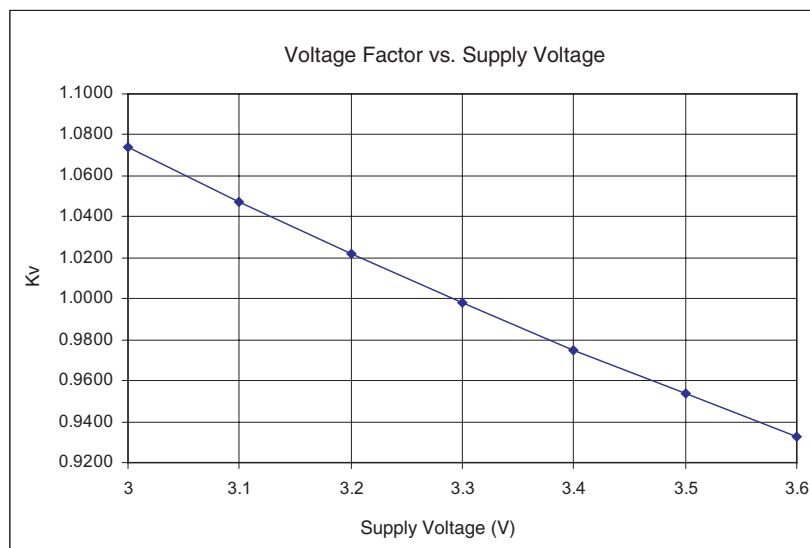


Figure 5: Voltage Factor vs. Supply Voltage

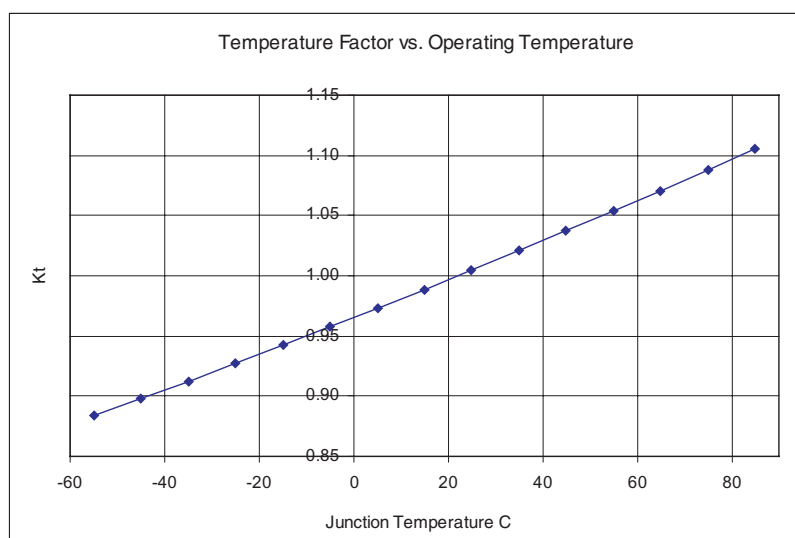


Figure 6: Temperature Factor vs. Operating Temperature

Power-up Sequencing

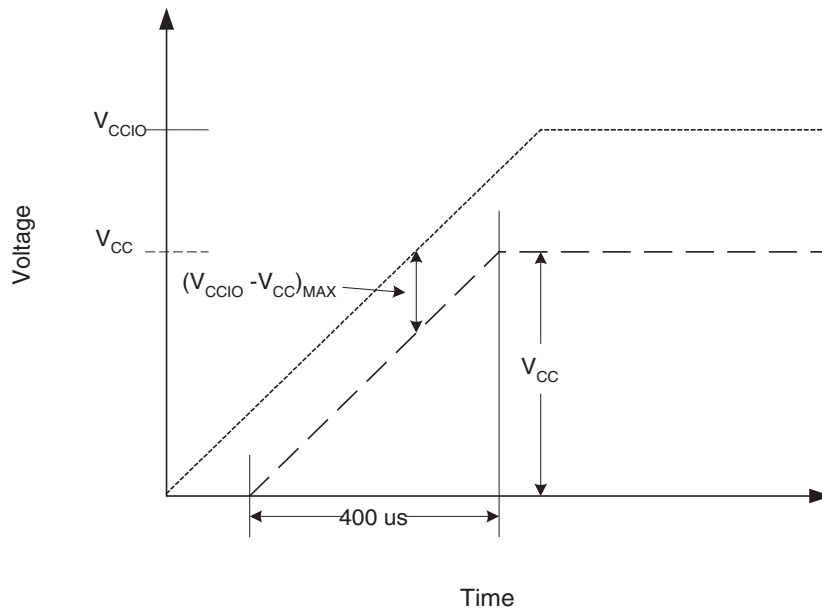


Figure 7: Power-up Requirements

The following requirements must be met when powering up the device:

(Refer to **Figure 7** above)

- When ramping up the power supplies keep $(V_{CCIO} - V_{CC})_{MAX} \leq 500 \text{ mV}$. Deviation from this recommendation can cause permanent damage to the device.
- V_{CCIO} must lead V_{CC} when ramping the device.
- The power supply must take greater than or equal to $400 \mu\text{s}$ to reach V_{CC} . Ramping to V_{CC}/V_{CCIO} earlier than $400 \mu\text{s}$ can cause the device to behave improperly.

An internal diode is present in-between V_{CC} and V_{CCIO} , as shown in **Figure 8**.

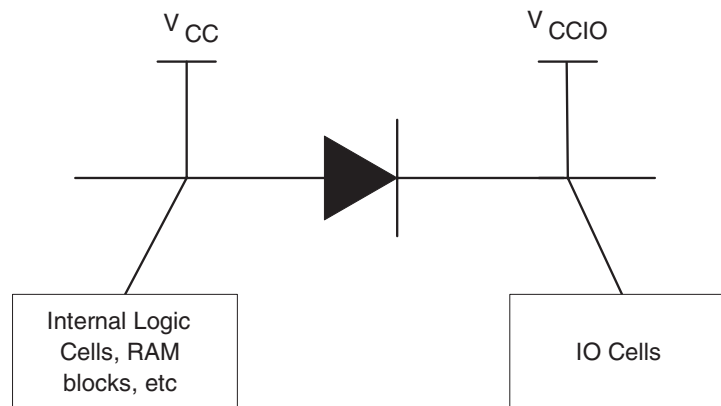


Figure 8: Internal Diode Between V_{CC} and V_{CCIO}

JTAG

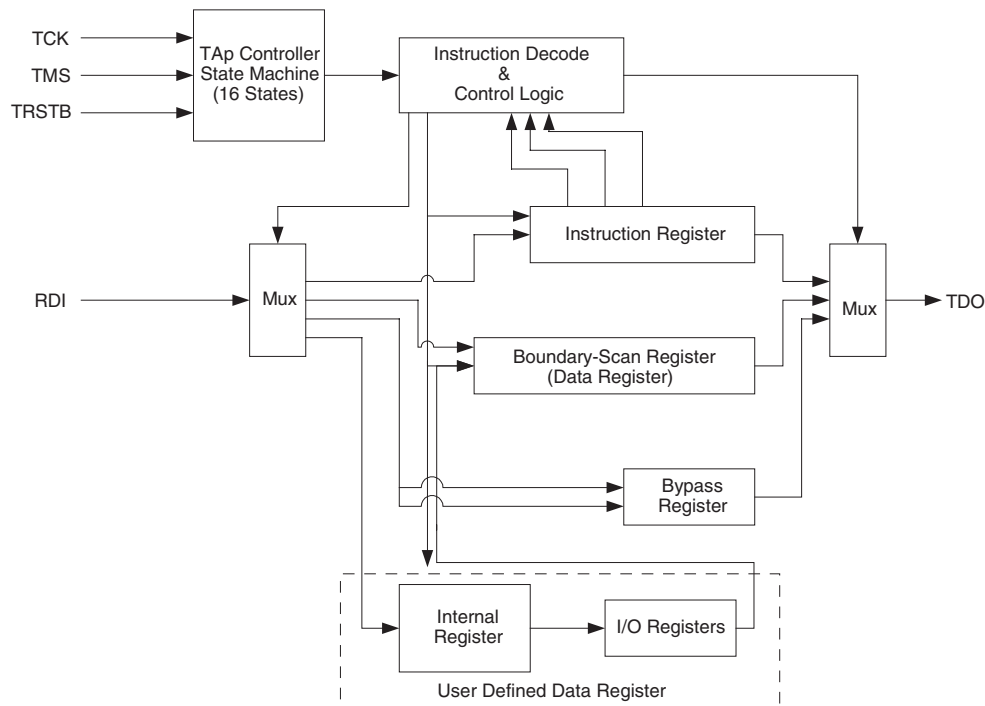


Figure 9: JTAG Block Diagram

Microprocessors and Application Specific Integrated Circuits (ASICs) pose many design challenges, not the least of which concerns the accessibility of test points. The Joint Test Access Group (JTAG) formed in response to this challenge, resulting in IEEE standard 1149.1, the Standard Test Access Port and Boundary Scan Architecture.

The JTAG boundary scan test methodology allows complete observation and control of the boundary pins of a JTAG-compatible device through JTAG software. A Test Access Port (TAP) controller works in concert with the Instruction Register (IR); these allow users to run three required tests, along with several user-defined tests.

JTAG tests allow users to reduce system debug time, reuse test platforms and tools, and reuse subsystem tests for fuller verification of higher level system elements.

The 1149.1 standard requires the following three tests:

- **Extest Instruction.** The Extest instruction performs a PCB interconnect test. This test places a device into an external boundary test mode, selecting the boundary scan register to be connected between the TAP's Test Data In (TDI) and Test Data Out (TDO) pins. Boundary scan cells are preloaded with test patterns (via the Sample/Preload Instruction), and input boundary cells capture the input data for analysis.
- **Sample/Preload Instruction.** This instruction allows a device to remain in its functional mode, while selecting the boundary scan register to be connected between the TDI and TDO pins. For this test, the boundary scan register can be accessed via a data scan operation, allowing users to sample the functional data entering and leaving the device.
- **Bypass Instruction.** The Bypass instruction allows data to skip a device's boundary scan entirely, so the data passes through the bypass register. The Bypass instruction allows users to test a device without passing through other devices. The bypass register is connected between the TDI and TDO pins, allowing serial data to be transferred through a device without affecting the operation of the device.

Pin Descriptions

Table 12: Pin Descriptions

Pin	Function	Description
TDI/RSI	Test Data In for JTAG /RAM init. Serial Data In	Hold HIGH during normal operation. Connects to serial PROM data in for RAM initialization. Connect to V _{CC} if unused.
TRSTB/RRO	Active low Reset for JTAG /RAM init. reset out	Hold LOW during normal operation. Connects to serial PROM reset for RAM initialization. Connect to GND if unused.
TMS	Test Mode Select for JTAG	Hold HIGH during normal operation. Connect to V _{CC} if not used for JTAG.
TCK	Test Clock for JTAG	Hold HIGH or LOW during normal operation. Connect to V _{CC} or ground if not used for JTAG.
TDO/RCO	Test data out for JTAG /RAM init. clock out	Connect to serial PROM clock for RAM initialization. Must be left unconnected if not used for JTAG or RAM initialization.
STM	Special Test Mode	Must be grounded during normal operation.
I/ACLK	High-drive input and/or array network driver	Can be configured as either or both.
I/GCLK	High-drive input and/or global network driver	Can be configured as either or both.
I	High-drive input	Use for input signals with high fanout.
I/O	Input/Output pin	Can be configured as an input and/or output.
V _{CC}	Power supply pin	Connect to 3.3 V supply.
V _{CCIO}	Input voltage tolerance pin	Connect to 5.0 V supply if 5 V input tolerance is required, otherwise connect to 3.3 V supply.
GND	Ground pin	Connect to ground.
GND/THERM	Ground/Thermal pin	Available on 456-PBGA only. Connect to ground plane on PCB if heat sinking desired. Otherwise may be left unconnected.

Ordering Information

QL 4090 - 1 PQ208 C

QuickLogic device

QuickRAM device

part number

Speed Grade

0 = Quick

1 = Fast

2 = Faster

3 = Faster

*4 = Wow

*Contact QuickLogic regarding availablity

Operating Range

C = Commercial

I = Industrial

M = Military

Package Code

PQ208 = 208-pin PQFP

CF208 = 208-pin CQFP

PQ240 = 240-pin PQFP

PB456 = 456-pin PBGA

208 and 240 PQFP Pinout Diagrams

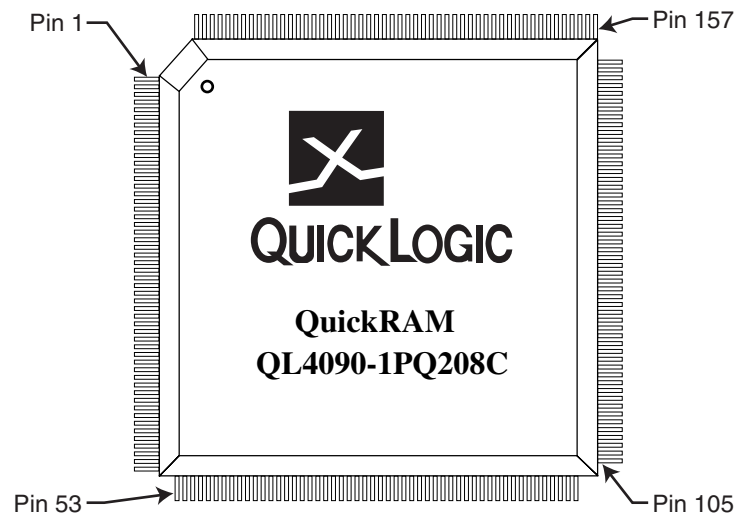


Figure 10: Top View of 208 Pin PQFP/CQFP

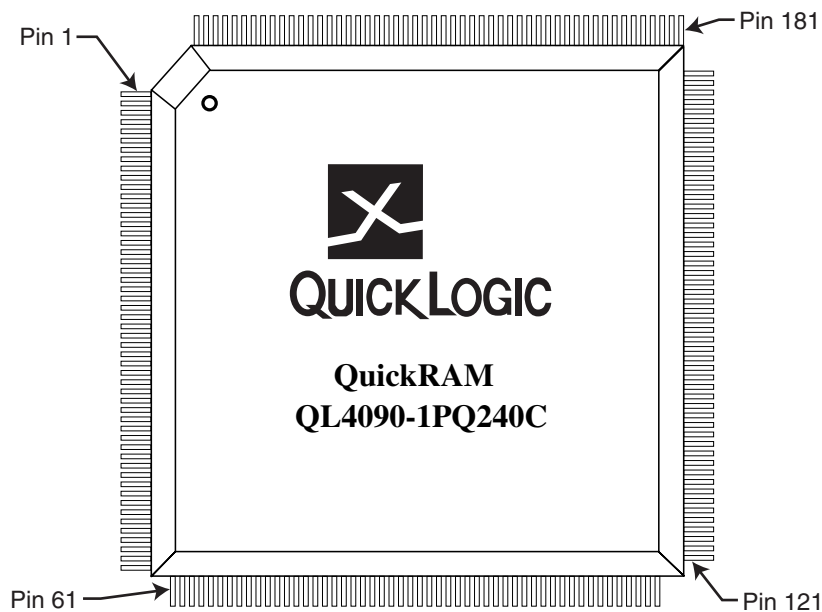


Figure 11: Top View of 240 Pin PQFP

208 and 240 PQFP Pinout Table

Table 13: 208/240 PQFP Pinout Table

240 PQFP	208 PQFP	Function	240 PQFP	208 PQFP	Function	240 PQFP	208 PQFP	Function	240 PQFP	208 PQFP	Function	240 PQFP	208 PQFP	Function
1	208	I/O	51	43	GND	98	84	I/O	145	125	I/O	194	168	I/O
2	1	I/O	52	44	I/O	99	85	I/O	146	126	I/O	195	169	I/O
3	2	I/O	53	45	I/O	100	86	I/O	147	127	GND	196	NC	I/O
4	3	I/O	54	46	I/O	101	87	I/O	148	128	I/O	197	170	I/O
5	4	I/O	55	47	I/O	102	88	I/O	149	NC	I/O	198	171	I/O
6	5	I/O	56	48	I/O	103	89	I/O	150	129	GLCK/I	199	172	I/O
7	NC	I/O	57	NC	I/O	104	90	I/O	151	130	ACLK/I	200	173	I/O
8	6	I/O	58	49	I/O	105	91	I/O	152	131	V _{CC}	201	174	I/O
9	7	I/O	59	50	I/O	106	92	I/O	153	132	GLCK/I	202	175	I/O
10	8	I/O	60	51	I/O	107	NC	I/O	154	133	GLCK/I	203	NC	I/O
11	9	I/O	NC	52	I/O	108	93	I/O	155	134	V _{CC}	204	176	I/O
12	10	V _{CC}	NC	53	I/O	109	94	I/O	156	135	I/O	205	177	GND
13	11	I/O	61	54	TDI	110	95	GND	157	136	I/O	206	178	I/O
14	12	GND	62	NC	I/O	NC	96	I/O	158	NC	I/O	207	179	I/O
15	13	I/O	63	NC	I/O	111	97	V _{CC}	159	137	I/O	208	NC	I/O
16	14	I/O	64	55	I/O	NC	98	I/O	160	NC	GND	209	180	I/O
17	NC	I/O	65	56	I/O	NC	99	I/O	161	138	I/O	210	181	I/O
18	15	I/O	66	NC	I/O	112	100	I/O	162	139	I/O	211	182	GND
19	16	I/O	67	57	I/O	113	NC	I/O	163	140	I/O	212	NC	V _{CC}
20	17	I/O	68	58	I/O	114	101	I/O	164	141	I/O	213	183	I/O
21	18	I/O	69	59	GND	115	NC	I/O	165	142	I/O	214	184	I/O
22	19	I/O	70	60	I/O	116	102	I/O	166	NC	I/O	215	185	I/O
23	20	I/O	71	61	V _{CC}	117	NC	I/O	167	143	I/O	216	186	I/O
24	NC	I/O	72	62	I/O	118	NC	I/O	168	144	I/O	217	187	V _{CCIO}
25	21	I/O	73	63	I/O	119	103	TRSTB	169	145	V _{CC}	218	188	I/O
26	22	I/O	74	64	I/O	120	104	TMS	170	NC	I/O	219	NC	I/O
27	23	GND	75	NC	I/O	121	105	I/O	171	146	I/O	220	189	I/O
28	24	I/O	76	65	I/O	122	NC	I/O	172	147	GND	221	190	I/O
29	25	GCLK/I	77	66	I/O	123	106	I/O	173	148	I/O	222	191	I/O
30	26	ACLK/I	78	67	I/O	124	107	I/O	174	149	I/O	223	192	I/O
31	27	V _{CC}	79	NC	I/O	125	108	I/O	175	150	I/O	224	193	I/O
32	28	GCLK/I	80	68	I/O	126	109	I/O	176	151	I/O	225	194	I/O
33	29	GCLK/I	81	69	I/O	127	NC	I/O	177	152	I/O	226	NC	I/O
34	30	V _{CC}	82	70	I/O	128	110	I/O	178	153	I/O	227	195	I/O
35	31	I/O	83	NC	I/O	129	111	I/O	179	154	I/O	228	196	I/O
36	32	I/O	NC	71	I/O	130	112	I/O	180	155	I/O	229	197	I/O
37	NC	GND	84	NC	I/O	131	113	I/O	NC	156	I/O	230	198	I/O
38	33	I/O	85	72	I/O	132	114	V _{CC}	181	157	TCK	231	NC	I/O
39	NC	I/O	86	73	GND	133	115	I/O	182	158	STM	232	199	GND
40	34	I/O	87	74	I/O	134	116	GND	183	NC	I/O	233	200	I/O
41	35	I/O	88	NC	V _{CC}	135	117	I/O	184	159	I/O	234	201	V _{CC}
42	36	I/O	89	75	I/O	136	NC	I/O	185	160	I/O	235	202	I/O
43	NC	I/O	90	76	I/O	137	118	I/O	186	161	I/O	236	203	I/O
44	37	I/O	91	77	I/O	138	119	I/O	187	162	I/O	237	204	I/O
45	38	I/O	92	78	GND	139	120	I/O	188	163	GND	238	205	I/O
46	39	I/O	93	79	I/O	140	121	I/O	189	164	I/O	239	206	I/O
47	NC	I/O	94	80	I/O	141	NC	I/O	190	165	V _{CC}	240	207	TDO
48	40	I/O	95	81	I/O	142	122	I/O	191	166	I/O			
49	41	V _{CC}	96	82	I/O	143	123	I/O	192	NC	I/O			
50	42	I/O	97	83	V _{CCIO}	144	124	I/O	193	167	I/O			

456 PBGA Pinout Diagram

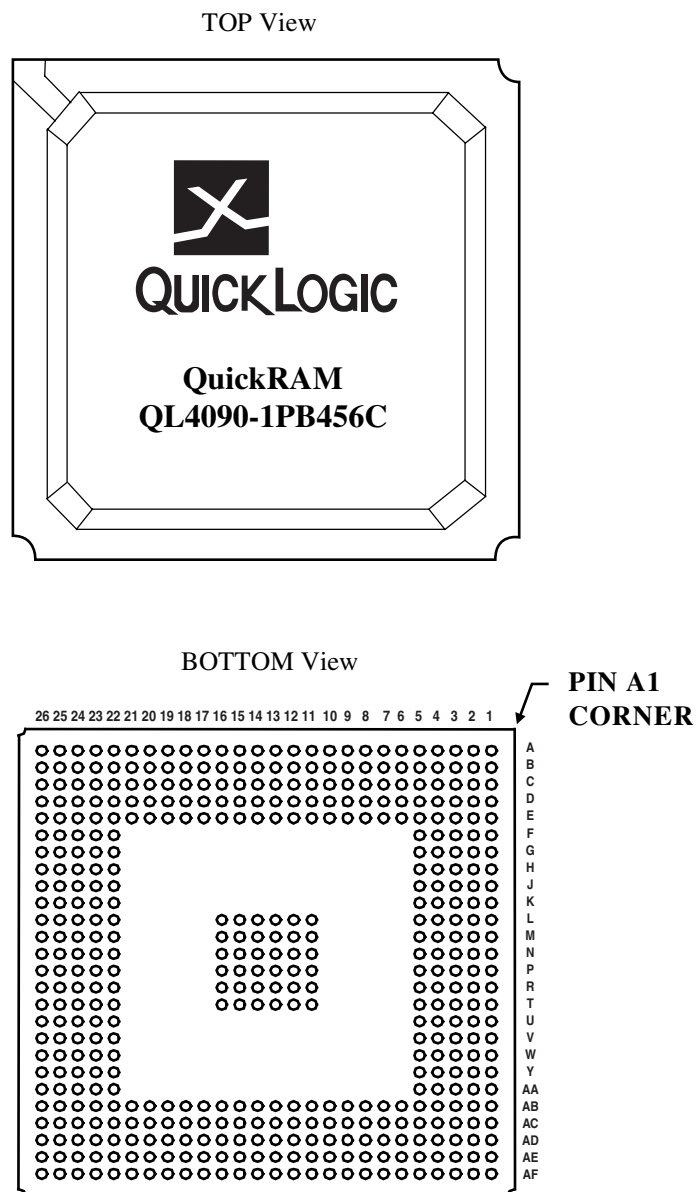


Figure 13: 456 PBGA Pinout Diagram

456 PBGA Pinout Table

Table 14: 456 PBGA Pinout Table

456	Function	456	Function	456	Function	456	Function	456	Function
A1	I/O	C1	I/O	E1	I/O	H23	I/O	M23	NC
A2	I/O	C2	I/O	E2	I/O	H24	I/O	M24	I/O
A3	I/O	C3	I/O	E3	I/O	H25	I/O	M25	I/O
A4	I/O	C4	TDO	E4	I/O	H26	I/O	M26	I/O
A5	I/O	C5	I/O	E5	GND	J1	I/O	N1	GCLK/I
A6	I/O	C6	I/O	E6	V _{CC}	J2	I/O	N2	I/O
A7	I/O	C7	I/O	E7	GND	J3	I/O	N3	I/O
A8	I/O	C8	I/O	E8	NC	J4	NC	N4	GCLK/I
A9	I/O	C9	I/O	E9	GND	J5	GND	N5	V _{CC}
A10	I/O	C10	I/O	E10	I/O	J22	NC	N11	GND/THERM
A11	I/O	C11	I/O	E11	GND	J23	NC	N12	GND/THERM
A12	V _{CCIO}	C12	I/O	E12	GND	J24	I/O	N13	GND/THERM
A13	I/O	C13	I/O	E13	V _{CC}	J25	I/O	N14	GND/THERM
A14	I/O	C14	I/O	E14	GND	J26	I/O	N15	GND/THERM
A15	I/O	C15	I/O	E15	GND	K1	I/O	N16	GND/THERM
A16	I/O	C16	I/O	E16	GND	K2	I/O	N22	GND
A17	I/O	C17	I/O	E17	NC	K3	I/O	N23	I/O
A18	I/O	C18	I/O	E18	GND	K4	I/O	N24	I/O
A19	I/O	C19	I/O	E19	NC	K5	V _{CC}	N25	I/O
A20	I/O	C20	I/O	E20	GND	K22	GND	N26	I/O
A21	I/O	C21	I/O	E21	V _{CC}	K23	I/O	P1	I/O
A22	I/O	C22	I/O	E22	GND	K24	I/O	P2	I/O
A23	I/O	C23	I/O	E23	I/O	K25	I/O	P3	I/O
A24	I/O	C24	I/O	E24	I/O	K26	I/O	P4	I/O
A25	I/O	C25	TCK	E25	I/O	L1	I/O	P5	NC
A26	I/O	C26	I/O	E26	I/O	L2	I/O	P11	GND/THERM
B1	I/O	D1	I/O	F1	I/O	L3	I/O	P12	GND/THERM
B2	I/O	D2	I/O	F2	I/O	L4	I/O	P13	GND/THERM
B3	I/O	D3	I/O	F3	I/O	L5	NC	P14	GND/THERM
B4	I/O	D4	GND	F4	NC	L11	GND/THERM	P15	GND/THERM
B5	I/O	D5	I/O	F5	V _{CC}	L12	GND/THERM	P16	GND/THERM
B6	I/O	D6	NC	F22	V _{CC}	L13	GND/THERM	P22	NC
B7	I/O	D7	I/O	F23	NC	L14	GND/THERM	P23	GCLK / I
B8	I/O	D8	I/O	F24	I/O	L15	GND/THERM	P24	GCLK / I
B9	I/O	D9	GND	F25	I/O	L16	GND/THERM	P25	I/O
B10	I/O	D10	I/O	F26	I/O	L22	NC	p26	ACLK/I
B11	I/O	D11	I/O	G1	I/O	L23	I/O	R1	I/O
B12	I/O	D12	GND	G2	I/O	L24	I/O	R2	I/O
B13	I/O	D13	I/O	G3	I/O	L25	I/O	R3	I/O
B14	I/O	D14	I/O	G4	I/O	L26	I/O	R4	NC
B15	I/O	D15	GND	G5	NC	M1	ACLK / I	R5	NC
B16	I/O	D16	I/O	G22	GND	M2	GCLK/I	R11	GND/THERM
B17	I/O	D17	I/O	G23	I/O	M3	I/O	R12	GND/THERM
B18	I/O	D18	GND	G24	I/O	M4	NC	R13	GND/THERM
B19	I/O	D19	I/O	G25	I/O	M5	GND	R14	GND/THERM
B20	I/O	D20	I/O	G26	I/O	M11	GND/THERM	R15	GND/THERM
B21	I/O	D21	NC	H1	I/O	M12	GND/THERM	R16	GND/THERM
B22	I/O	D22	I/O	H2	I/O	M13	GND/THERM	R22	V _{CC}
B23	I/O	D23	GND	H3	I/O	M14	GND/THERM	R23	NC
B24	I/O	D24	I/O	H4	I/O	M15	GND/THERM	R24	I/O
B25	I/O	D25	I/O	H5	NC	M16	GND/THERM	R25	I/O
B26	STM	D26	I/O	H22	NC	M22	NC	R26	GCLK / I

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Table 14: 456 PBGA Pinout Table (Continued)

456	Function	456	Function	456	Function	456	Function	456	Function
T1	I/O	W5	NC	AB15	V _{CC}	AD3	I/O	AE17	I/O
T2	I/O	W22	NC	AB16	I/O	AD4	I/O	AE18	I/O
T3	I/O	W23	I/O	AB17	NC	AD5	I/O	AE19	I/O
T4	I/O	W24	I/O	AB18	V _{CC}	AD6	I/O	AE20	I/O
T5	V _{CC}	W25	I/O	AB19	GND	AD7	I/O	AE21	I/O
T11	GND/THERMAL	W26	I/O	AB20	NC	AD8	I/O	AE22	I/O
T12	GND/THERMAL	Y1	I/O	AB21	V _{CC}	AD9	I/O	AE23	NC
T13	GND/THERMAL	Y2	I/O	AB22	GND	AD10	I/O	AE24	TMS
T14	GND/THERMAL	Y3	I/O	AB23	I/O	AD11	I/O	AE25	I/O
T15	GND/THERMAL	Y4	I/O	AB24	I/O	AD12	I/O	AE26	I/O
T16	GND/THERMAL	Y5	I/O	AB25	I/O	AD13	I/O	AF1	I/O
T22	GND	Y22	GND	AB26	I/O	AD14	I/O	AF2	I/O
T23	I/O	Y23	I/O	AC1	I/O	AD15	I/O	AF3	I/O
T24	I/O	Y24	I/O	AC2	I/O	AD16	I/O	AF4	I/O
T25	I/O	Y25	I/O	AC3	NC	AD17	I/O	AF5	I/O
T26	I/O	Y26	I/O	AC4	GND	AD18	I/O	AF6	I/O
U1	I/O	AA1	I/O	AC5	I/O	AD19	I/O	AF7	I/O
U2	I/O	AA2	I/O	AC6	NC	AD20	I/O	AF8	I/O
U3	I/O	AA3	NC	AC7	I/O	AD21	I/O	AF9	I/O
U4	I/O	AA4	NC	AC8	I/O	AD22	I/O	AF10	I/O
U5	GND	AA5	V _{CC}	AC9	NC	AD23	TRSTB	AF11	I/O
U22	NC	AA22	V _{CC}	AC10	I/O	AD24	I/O	AF12	I/O
U23	I/O	AA23	NC	AC11	I/O	AD25	I/O	AF13	I/O
U24	I/O	AA24	I/O	AC12	NC	AD26	I/O	AF14	I/O
U25	I/O	AA25	I/O	AC13	I/O	AE1	TDI	AF15	I/O
U26	I/O	AA26	I/O	AC14	V _{CCIO}	AE2	I/O	AF16	I/O
V1	I/O	AB1	I/O	AC15	NC	AE3	I/O	AF17	I/O
V2	I/O	AB2	I/O	AC16	I/O	AE4	I/O	AF18	I/O
V3	I/O	AB3	I/O	AC17	I/O	AE5	I/O	AF19	I/O
V4	NC	AB4	I/O	AC18	NC	AE6	I/O	AF20	I/O
V5	NC	AB5	GND	AC19	I/O	AE7	I/O	AF21	I/O
V22	GND	AB6	V _{CC}	AC20	I/O	AE8	I/O	AF22	I/O
V23	NC	AB7	NC	AC21	I/O	AE9	I/O	AF23	I/O
V24	I/O	AB8	NC	AC22	NC	AE10	I/O	AF24	I/O
V25	I/O	AB9	NC	AC23	GND	AE11	I/O	AF25	I/O
V26	I/O	AB10	V _{CC}	AC24	I/O	AE12	I/O	AF26	I/O
W1	I/O	AB11	GND	AC25	I/O	AE13	I/O		
W2	I/O	AB12	NC	AC26	I/O	AE14	I/O		
W3	I/O	AB13	I/O	AD1	I/O	AE15	I/O		
W4	I/O	AB14	GND	AD2	NC	AE16	I/O		

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Revision History

Table 15: Revision History

Revision	Date	Comments
A	not avail.	First release.
B	not avail.	
C	not avail.	
D	not avail.	
E	not avail.	
F	May 2000	
G	April 2002	Update of AC/DC Specs and reformat
H	May 2002	Added Kfactor, Power-up, JTAG and mechanical drawing information. Reformatted.

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